

April 2000

FQB2P25 / FQI2P25

250V P-Channel MOSFET

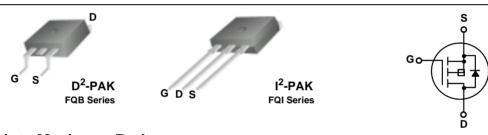
General Description

These P-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters.

Features

- -2.3A, -250V, $R_{DS(on)}$ = 4.0 Ω @V_{GS} = -10 V Low gate charge (typical 6.5 nC)
- Low Crss (typical 6.5 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQB2P25 / FQI2P25	Units
V _{DSS}	Drain-Source Voltage		-250	V
I _D	Drain Current - Continuous (T _C = 25°C)		-2.3	Α
	- Continuous (T _C = 100°C	C)	-1.45	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	-9.2	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	120	mJ
I _{AR}	Avalanche Current	(Note 1)	-2.3	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.2	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-5.5	V/ns
P _D	Power Dissipation (T _A = 25°C) *		3.13	W
	Power Dissipation (T _C = 25°C)		52	W
	- Derate above 25°C		0.42	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

^{*} When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-250			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = -250 μA, Referenced to 25°C		-0.2		V/°C
I _{DSS}	Zara Oata Valta va Basis Oassat	V _{DS} = -250 V, V _{GS} = 0 V			-1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = -200 V, T _C = 125°C			-10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-3.0		-5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = -10 V, I _D = -1.15 A	!	3.15	4.0	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = -40 \text{ V}, I_D = -1.15 \text{ A}$ (Note 4)	-	1.2		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		190 40 6.5	250 55 8.5	pF pF
	ing Characteristics			0.0	0.0	ρı
t _{d(on)}	Turn-On Delay Time	V _{DD} = -125 V, I _D = -2.3 A,		8.5	25	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$	-	40	90	ns
t _{d(off)}	Turn-Off Delay Time	- 1.G - 20	1	12	35	ns
t _f	Turn-Off Fall Time	(Note 4, 5)	-	25	60	ns
Qg	Total Gate Charge	V _{DS} = -200 V, I _D = -2.3 A,		6.5	8.5	nC
Q _{gs}	Gate-Source Charge	V _{GS} = -10 V		1.8		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)	1	3.0		nC
	ource Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				-2.3	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F				-9.2	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -2.3 \text{ A}$			-5.0	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = -2.3 \text{ A,}$		110		ns
Q_{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note 4)		0.4		μC

- $\label{eq:Notes:1} \begin{array}{ll} \textbf{Notes:} \\ \textbf{1.} \ \ \text{Repetitive Rating: Pulse width limited by maximum junction temperature} \\ \textbf{2.} \ \ \textbf{L} = 36\text{mH, } \ \textbf{I}_{AS} = -2.3\text{A, } \ \textbf{J}_{DD} = -50\text{V, } \ \textbf{R}_{C} = 25\ \Omega, \ \text{Starting } \ \textbf{T}_{J} = 25^{\circ}\text{C} \\ \textbf{3.} \ \ \textbf{I}_{SD} \leq -2.3\text{A, } \ \text{di/dt} \leq 300\text{A/}\mu\text{s, } \ \textbf{V}_{DD} \leq \text{BV}_{DSS}, \ \text{Starting } \ \textbf{T}_{J} = 25^{\circ}\text{C} \\ \textbf{4.} \ \ \text{Pulse Test: Pulse width} \leq 300\mu\text{s, } \ \text{Dt cycle} \leq 2\% \\ \textbf{5.} \ \ \ \text{Essentially independent of operating temperature} \end{array}$

Typical Characteristics

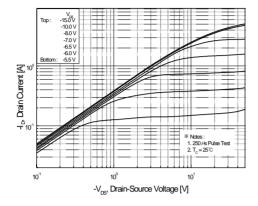


Figure 1. On-Region Characteristics

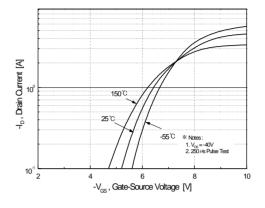


Figure 2. Transfer Characteristics

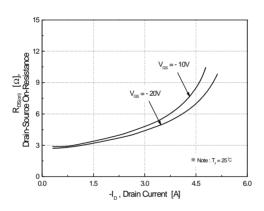


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

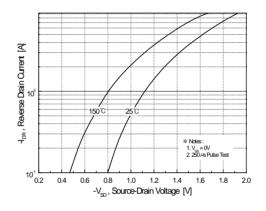


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

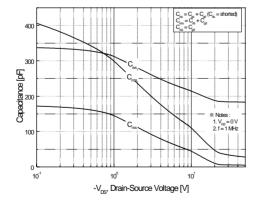


Figure 5. Capacitance Characteristics

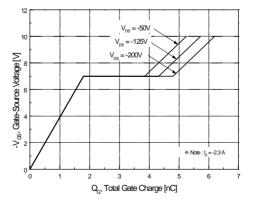
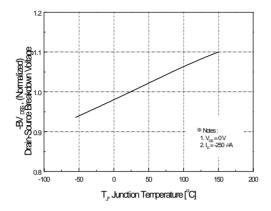


Figure 6. Gate Charge Characteristics





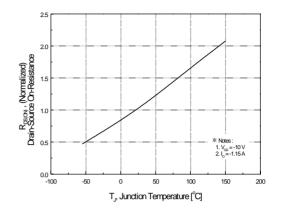
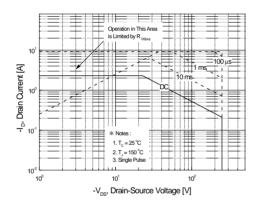


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



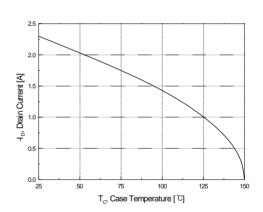


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

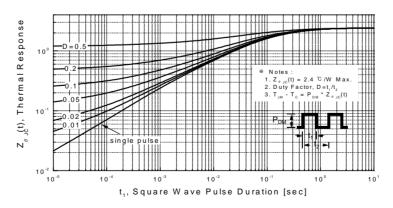
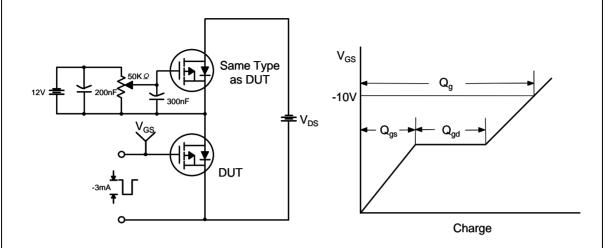


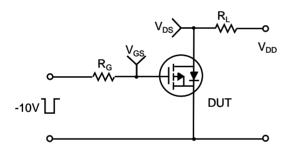
Figure 11. Transient Thermal Response Curve

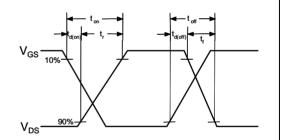
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Gate Charge Test Circuit & Waveform

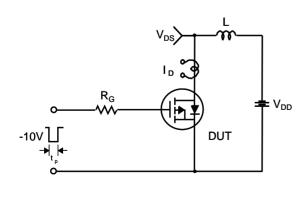


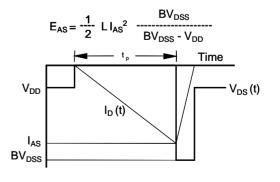
Resistive Switching Test Circuit & Waveforms



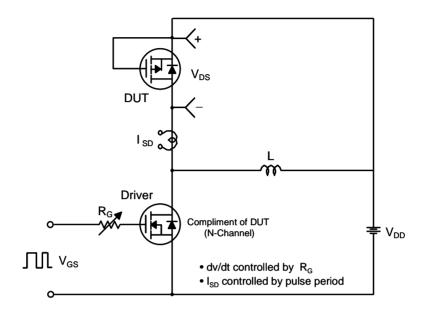


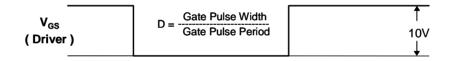
Unclamped Inductive Switching Test Circuit & Waveforms



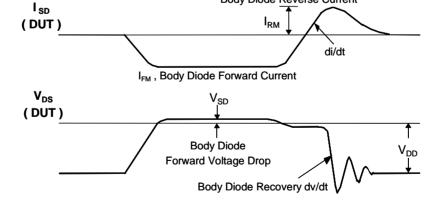


Peak Diode Recovery dv/dt Test Circuit & Waveforms

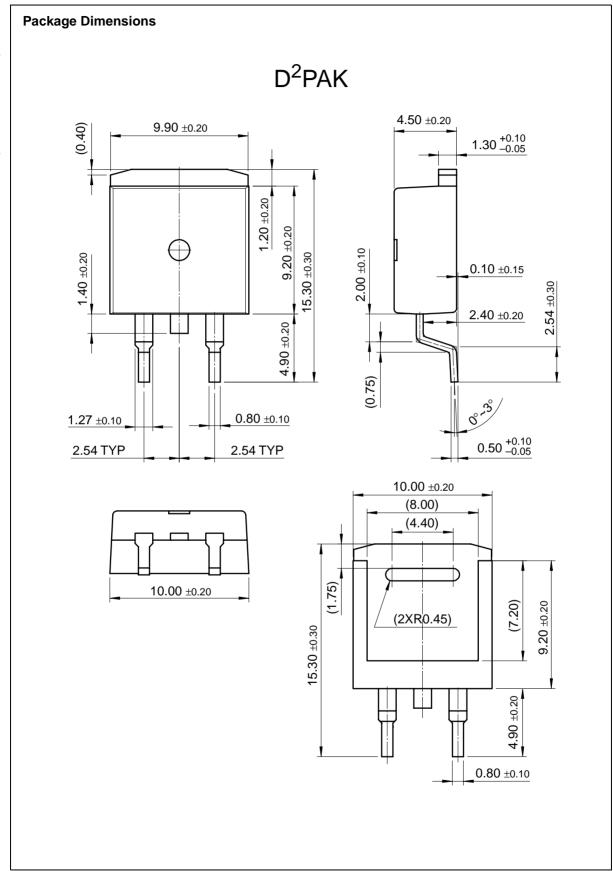


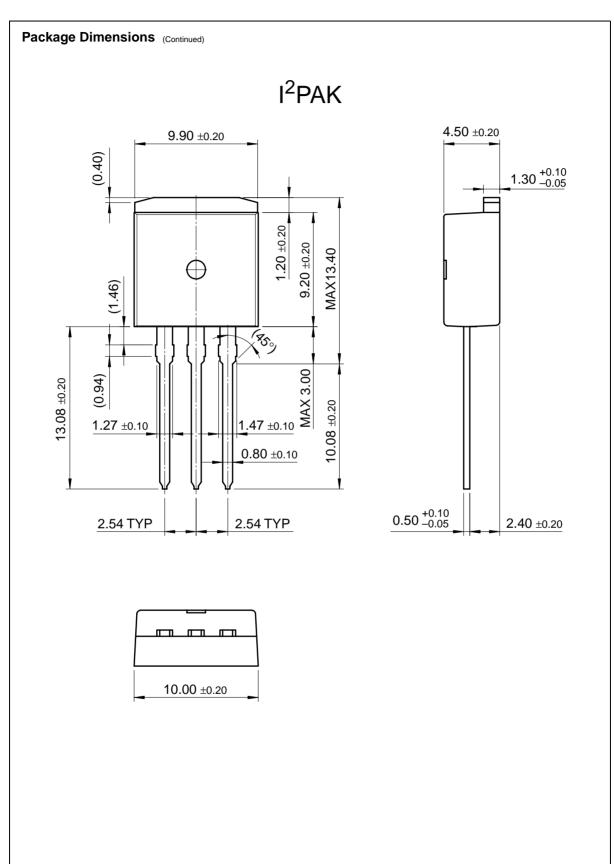


Body Diode Reverse Current



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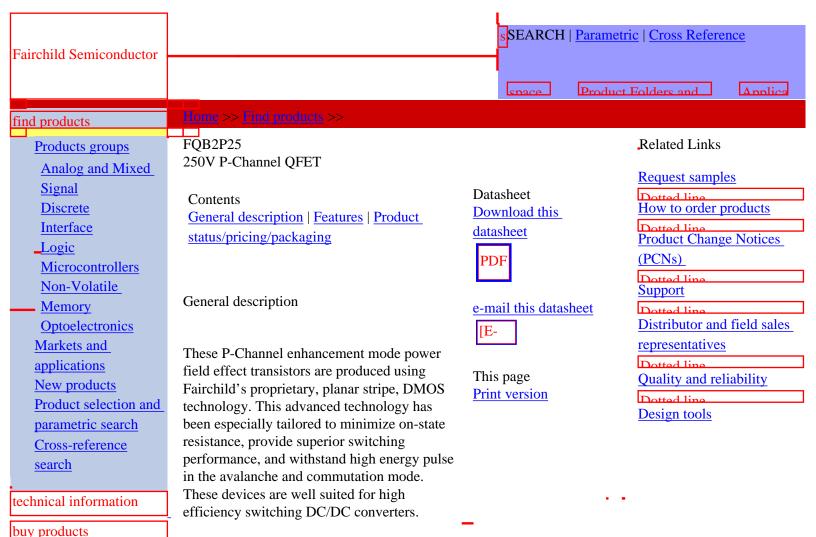
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back to top

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Features

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back to top

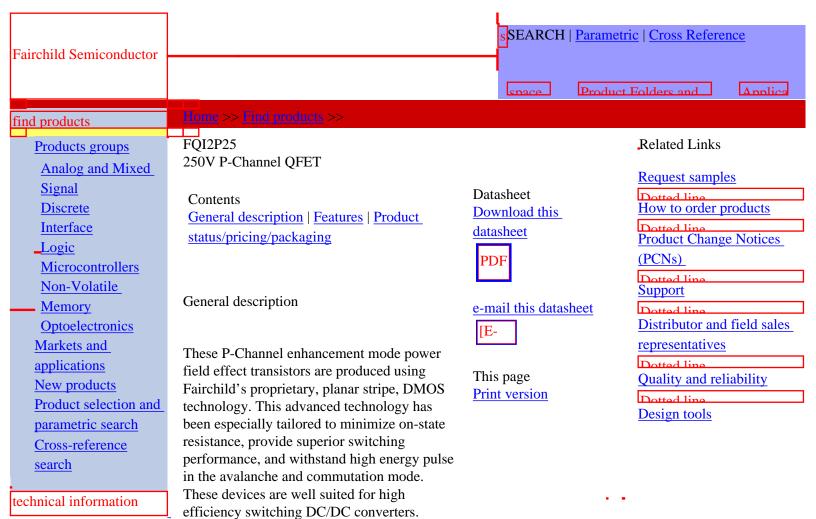
Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQB2P25TM	Full Production	\$0.489	TO-263(D2PAK)	2	TAPE REEL

^{* 1,000} piece Budgetary Pricing

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back to top

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Product	Product status	Pricing*	Package type	Leads	Packing method
FQI2P25TU	Full Production	\$0.489	TO-262(I2PAK)	3	RAIL

^{* 1,000} piece Budgetary Pricing

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back to top